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**Connected
Equipment Summit**



The Intelligent Equipment Era

Secure, Connected, Autonomous

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Agenda

1. Industry today
2. Future of the PDF Solutions Equipment Products
3. Case Studies
4. Future Outlook

#1.

Industry Today

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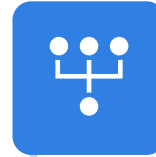
Industry Trends



**Multi-
platform**



AI/ML



**Digital
Twins**



Debugging



Testing



**Remote
connectivity**



Cybersecurity

Industry at a Crossroads

1. AI; EVs; High-Performance Computing (HPC); Data Centers **driving demand**



2. **Complexity exploding** across fabs, OEMs, OSATs



3. Equipment remains **siloed, underutilized, and vulnerable**



Opportunity: redefine factories as ecosystems of intelligent equipment

#2.

Future of the PDF Solutions Equipment Products

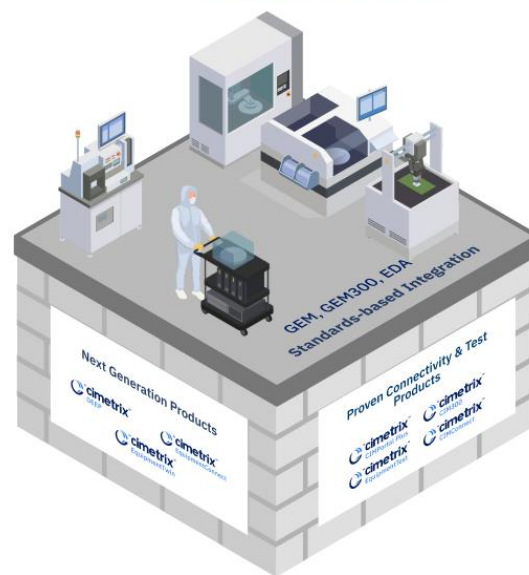
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OSAT/ PACKAGING

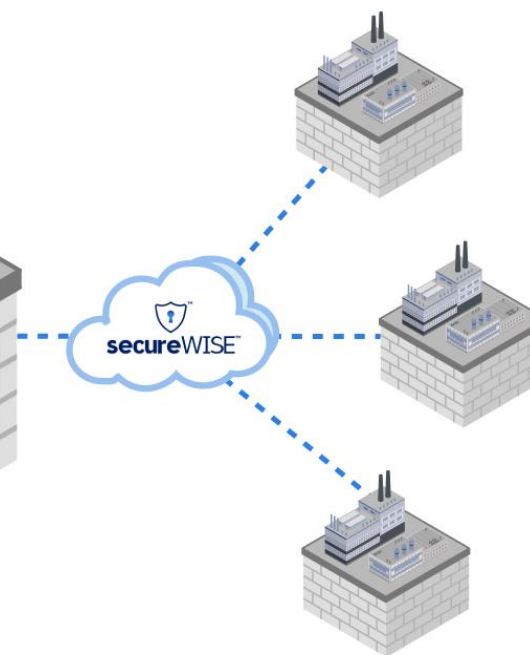
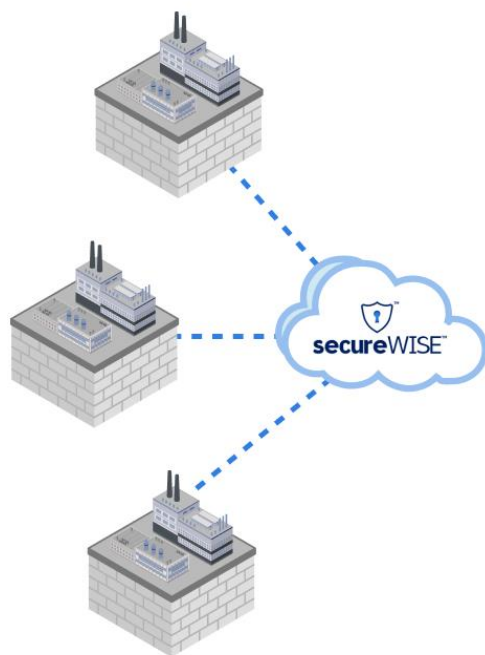
- 99% 300mm Fabs
- 100+ OEMs Connected
- Centralized Access
- High Tool Uptime
- Double Encryption
- IP Protection
- Remote Collaboration
- Secure Monitoring
- Full Audit Trail
- Lower Service Costs

FAB ADMIN/ BACK OFFICE



FAB

EQUIPMENT SUPPLIERS



#3.

Case Studies

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Case Study: OEM

Global OEM

WHO



**Centralized
Monitoring**

**Automated
Mediation**

**Remote
troubleshooting**

WHAT



**Less
Downtime**

**Lower
Cost**

**Travel
minimized**

**Faster Issue
Resolution**

RESULT



Case Study: FAB

U.S. fab: 550+ tools across 6 sites

WHO



Real-time monitoring & compliance

Engineers collaborate across 3 time zones

WHAT



Reduced Travel

Scalable Training

RESULT



Case Study: Unified Adoption

Major IDM standardizing on secureWISE

WHO



21,000 tools connected
in 3 years

900+ frameworks
deployed

WHAT



Zero trust → no inbound VPNs, full audit

RESULT



#4.

Future Outlook

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Industry Evolution

Automation

PLCs

Robotics

IT

Smart Factories

IoT

Cloud

Analytics

Intelligent Equipment

Secure

Connected

Autonomous

Autonomous Fab Vision



Secure remote operations
standard



AI-driven predictive
maintenance



Self-healing equipment



Immersive VR/AR
collaboration



Unified backbone across
fabs, OEMs, OSATs

PDF/SOLUTIONS™

the leading commercial data, analytics, and mission critical platform
spanning the semiconductor and electronics industry



Neutral, trusted backbone



**Connecting fabs, OEMs,
OSATs, fabless**



**Delivering connectivity,
automation, intelligence**

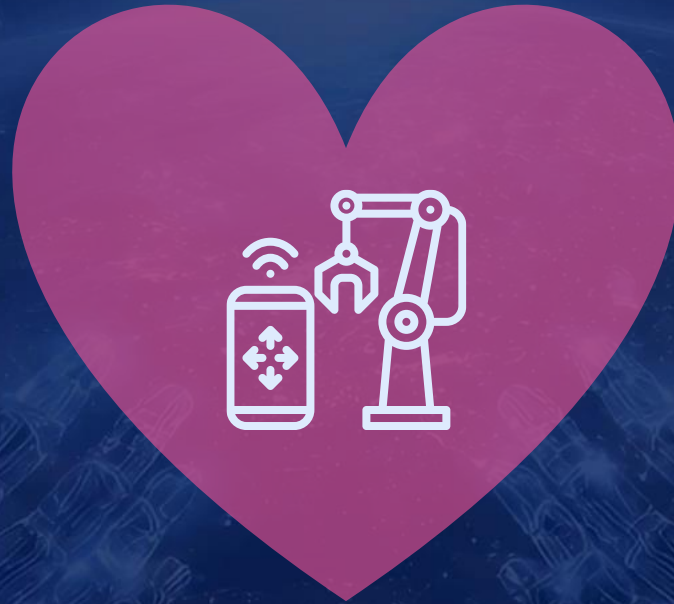


**Equipment = hub of The
Intelligent Equipment Era**



The Future Factory

Secure. Connected. Intelligent.



PDF/sOLUTIONS® will lead the way. **Join Us.**

Over 200 PDF Equipment Customers

Includes:



55K+ Equipment
Installs &
150K Factory
Connections!

Broad Market Adoption

Last year PDF equipment software was installed on **over 7,600 systems**

This year over 8,000 semiconductor **systems** will ship with PDF equipment software including...

- Metrology
- ALD/EPI/Etch
- Pick & Place
- Cleaning/Strip
- Backend Test
- MOCVD & PVD
- Inspection
- Bonding
- Photovoltaic
- Electrochemical Deposition
- Ion Implant
- Lithography



***The largest OEM** in this industry shipped their software on approximately **6k pieces of equipment**

The Equipment Software Stack for the Intelligent Software



Secure Connectivity



Automation & Control



Digital Intelligence



AI/ML-driven
Resilience

Cutting-Edge Solutions for Semiconductor Innovation



- Equipment control software toolkit
- Streamlines equipment integration and automation



- Diagnostically Enhanced Equipment Protection
- Enhances equipment reliability and reduces downtime



- Real-time digital replica for predictive maintenance and optimization
- Improves operational efficiency through data-driven insights

Simplified DEEP Heater Example

Setpoint (SP) and Process Variable (PV)

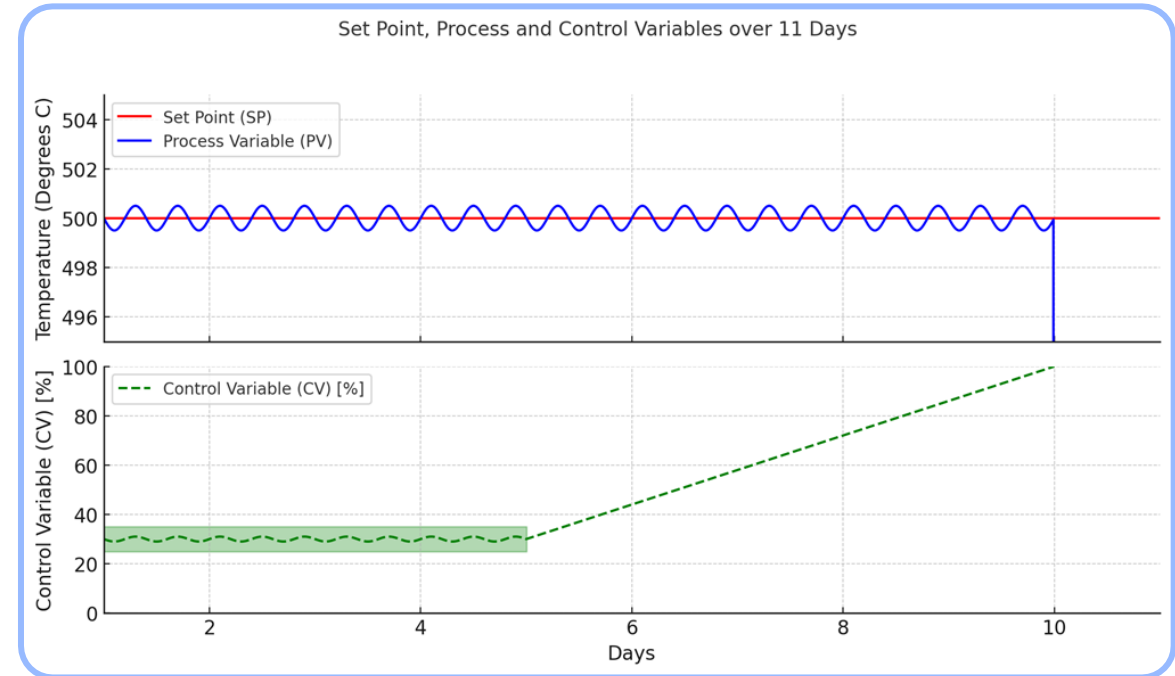
- Routinely accessible for operational reference.
- Continuously surveilled to detect operational discrepancies

Control Variable (CV)

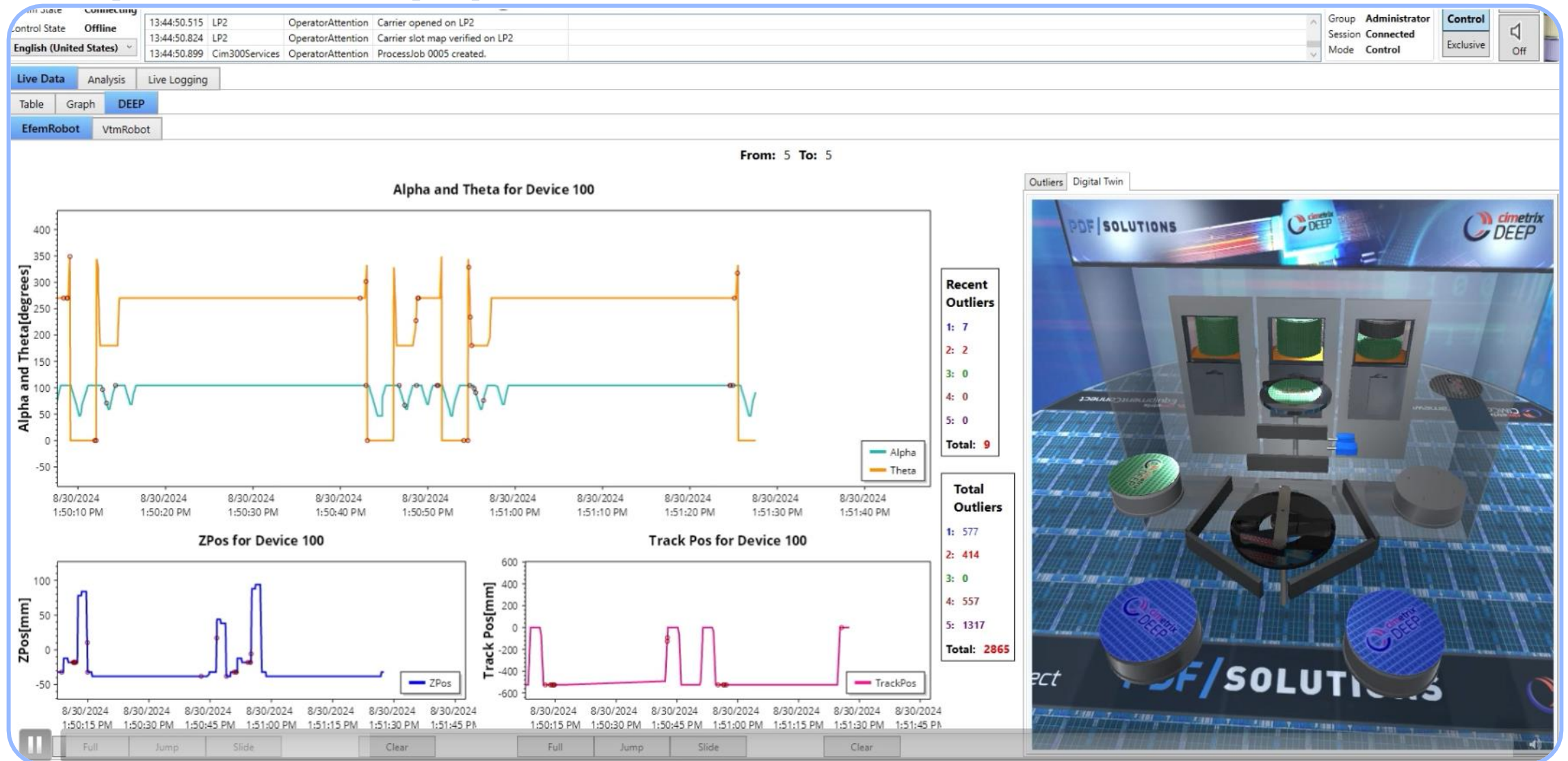
- Traditionally not recorded or observed.
- Reflects the output of control algorithms, crucial for aligning the PV with the SP

Innovative Strategy by DEEP

- Implements AI/ML to consistently monitor CV patterns.
- Integrates analysis of the setpoint and process variable for comprehensive oversight.
- Proactively identifies potential heater issues up to five days in advance, enhancing predictive maintenance.



CCF/ECF with EquipmentTwin & DEEP!



Robot Use Case



MCBF – 11,000,000

- Assuming 24/7 1 cycle/sec implies 86,400 cycles per day
- Failure every 127 days if no PM thus schedule PM every 90 days
- 1 Day for PM on a 300wph equipment would cost 7,200 wafers at \$3,000 per wafer implies \$21.6M per PM or 4 PMs per year or total cost of \$86.4M

Predict Failures Before They Happen

**Golden Robot
Fingerprints Would allow
less frequent PMs**

**If Increase to 120 days or
3 PMs per year Fab saves
1PM or \$21.6M**

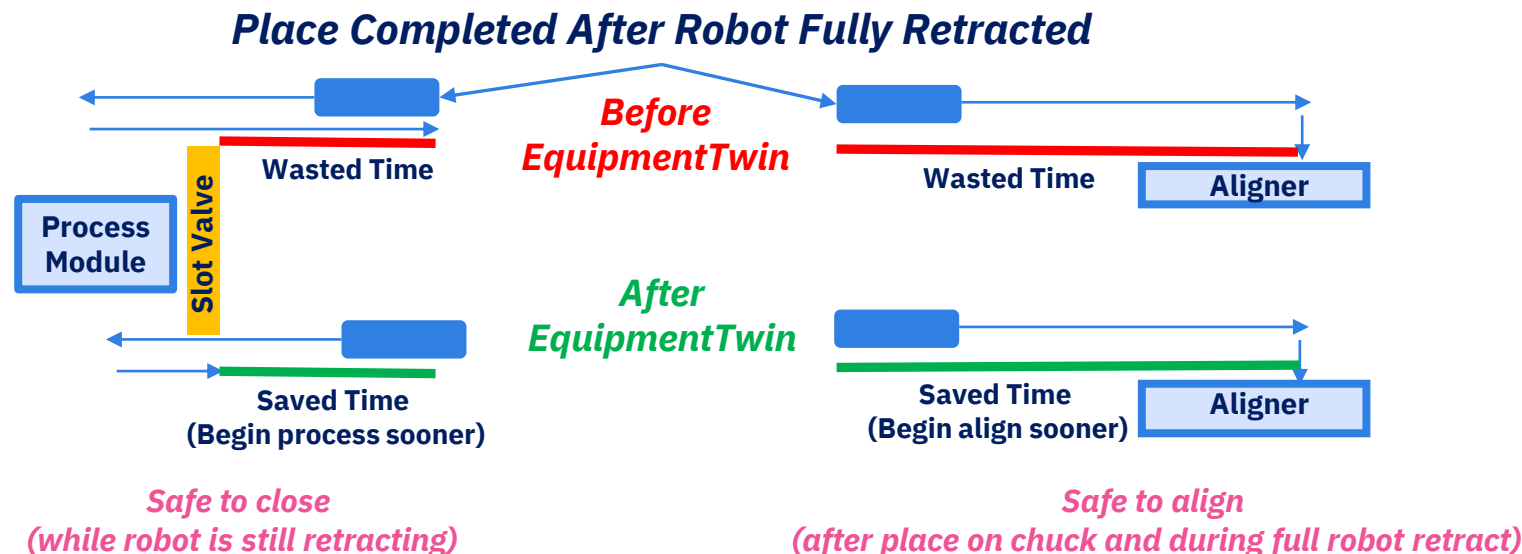


Throughput Improvement (Patent Pending)

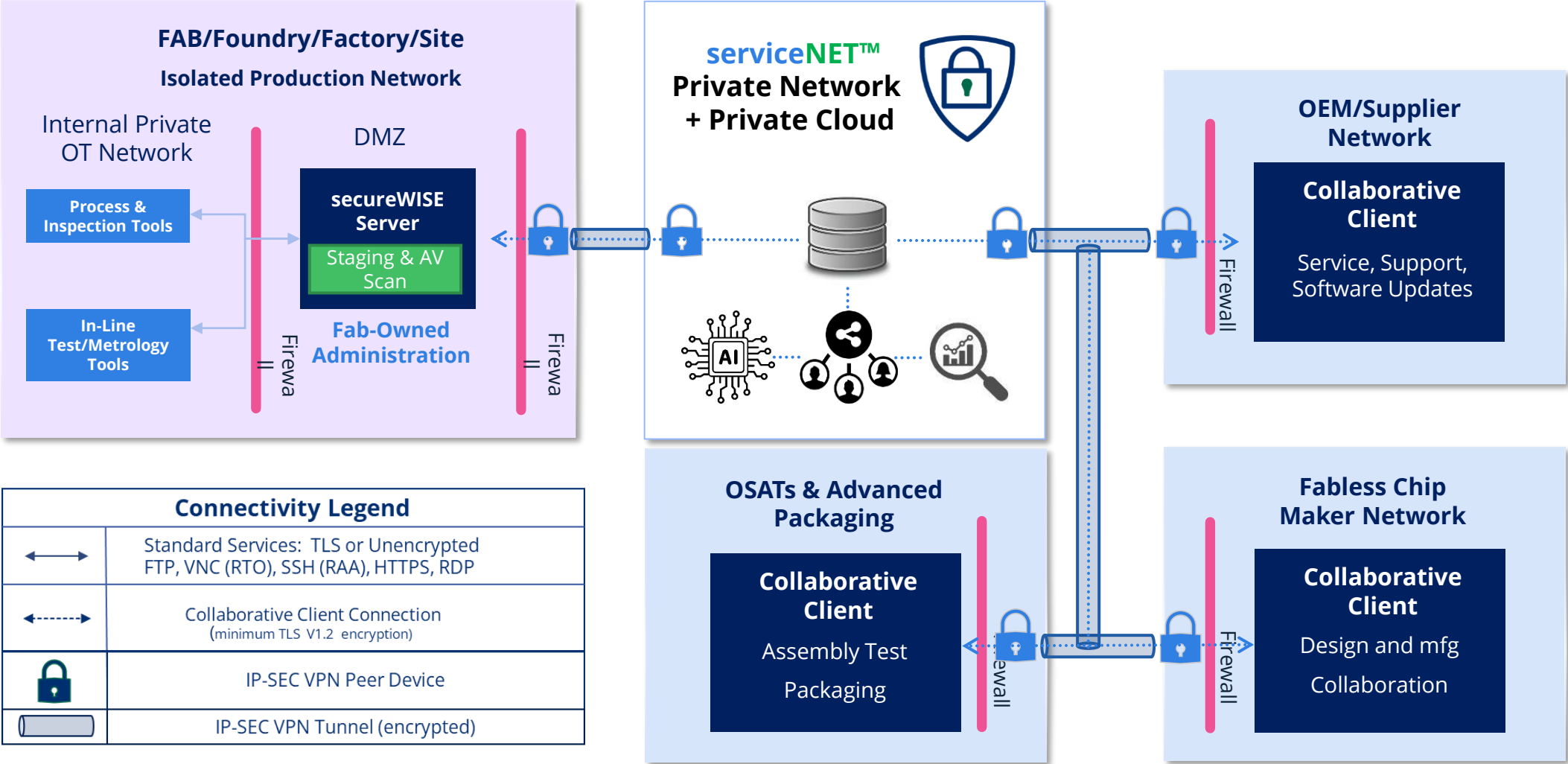
Scenario	Time per Wafer (Seconds)	Throughput (Wafers/Hour)	% Improvement
Original Process	12	300	NA
First Optimization	11	327	9%
Second Optimization	10	360	20%
Significant ET Improvement	8	450	50%

EquipmentTwin's slot valve and aligner optimizations

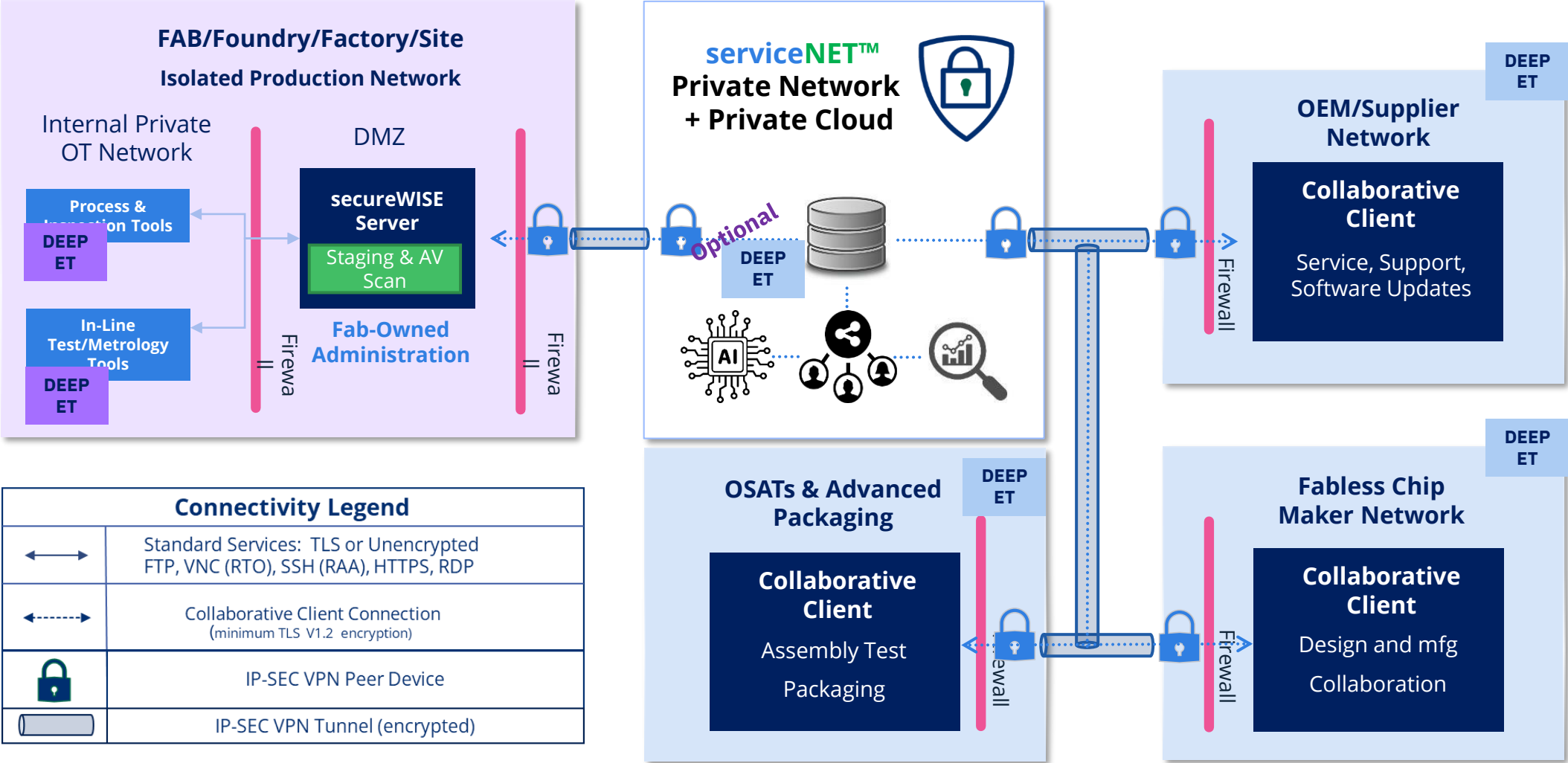
- Even 2 seconds per move improvement results in significant throughput improvement (20%)
- increased production capacity
- reduced cost of ownership



Secure Private Cloud – Empowered with DEEP & EquipmentTwin



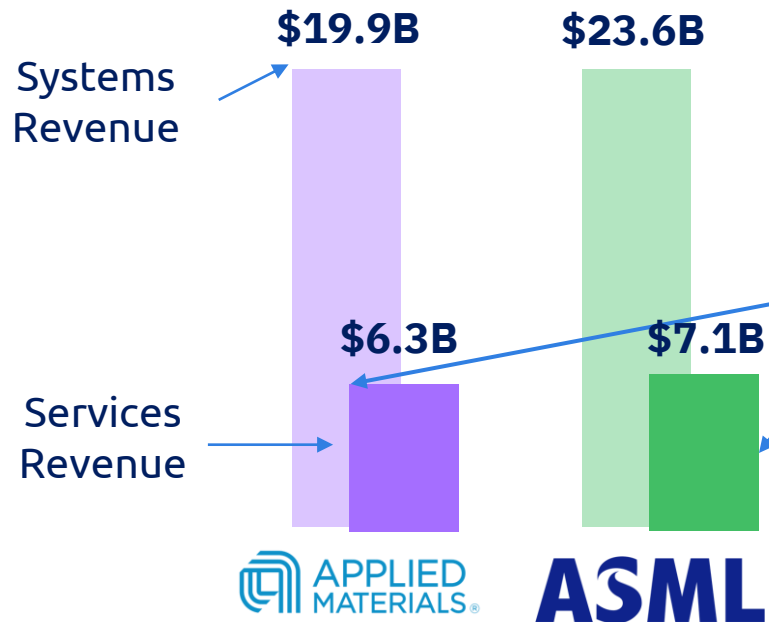
Secure Private Cloud – Empowered with DEEP & EquipmentTwin



Semiconductor Market Size

\$627.6B
Total Global
semiconductor market

\$117B
WFE Market



- **Service Growth Exponentially Increasing**
 - AMAT – 2013 \$2B, 2019 \$4B 2024 \$6.3B
 - ASML – 2013 \$1.7B, 2019 \$2.5B, 2024 \$7.1B
- **Recurring Service Revenue from Top 2 OEMs - \$13.4B**

Thank You

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